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FS - EPI

IC - H01L23/04 ; H01L25/00

MC - U11-D01A4 U14-H03C2A

PA - (KYOC) KYOCERA CORP

PN - JP9237867 A 19970909 DW199746 H01L25/00 005pp

PR - JP19960042528 19960229

XIC - H01L-023/04 ; H01L-025/00

XP - N1997-417255

AB - J09237867 The package (1) consists of a antenna circuit substrate (A) and a high frequency device circuit substrate (B). The antenna circuit substrate incorporates a first dielectric substrate (2) and a high frequency line (4). An antenna element (3) is mounted on the first dielectric substrate. Power is supplied to first dielectric substrate antenna element. The high frequency device circuit substrate incorporates a second dielectric substrate (7) with a cavity (8) and a transmission line (11).

- The cavity accommodates a high frequency device (9). A ground layer is formed at the junction of antenna circuit substrate and high frequency device circuit substrate. The high frequency line of antenna circuit substrate is connected to the transmission line in high frequency device circuit substrate by magnetic coupling.

- ADVANTAGE - Reduces loss as line connecting antenna circuit to high frequency device circuit is shortened. Secures compact package.

- (Dwg.1/4)

IW - PACKAGE HF DEVICE COUPLE HIGH FREQUENCY LINE ANTENNA CIRCUIT SUBSTRATE
TRANSMISSION LINE HIGH FREQUENCY DEVICE CIRCUIT SUBSTRATE MAGNETIC

IKW - PACKAGE HF DEVICE COUPLE HIGH FREQUENCY LINE ANTENNA CIRCUIT SUBSTRATE
TRANSMISSION LINE HIGH FREQUENCY DEVICE CIRCUIT SUBSTRATE MAGNETIC

NC - 001

OPD - 1996-02-29

ORD - 1997-09-09

PAW - (KYOC) KYOCERA CORP

TI - Package for HF device - couples high frequency line within antenna circuit substrate with transmission line within high frequency device circuit substrate magnetically